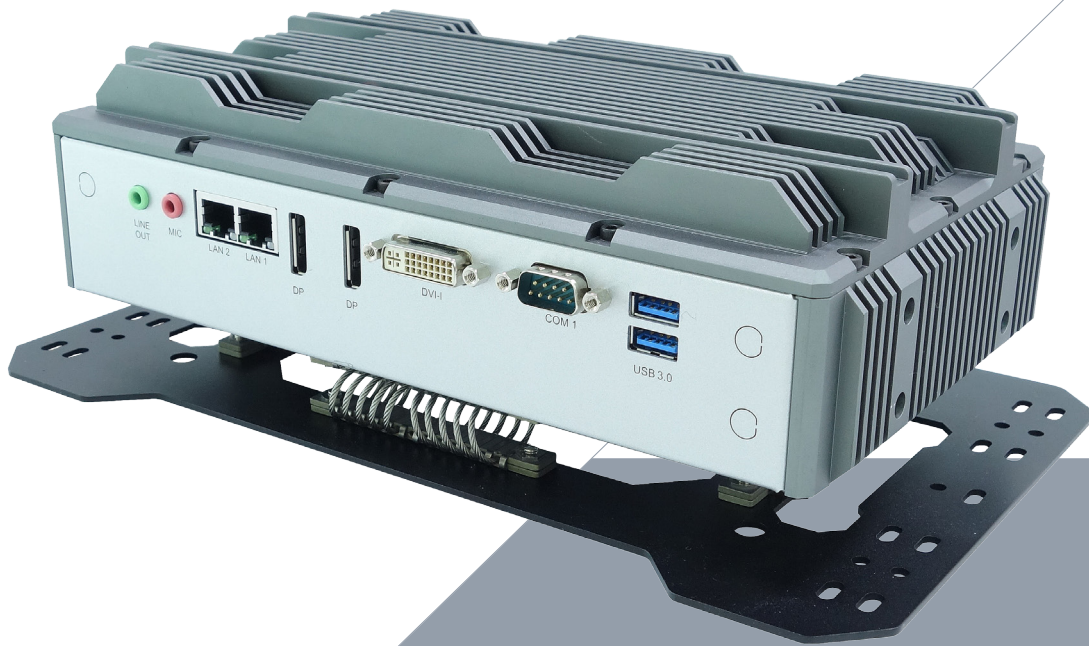


# SR10A

## MIL-STD-810G RUGGED FANLESS COMPUTER WITH ULTRA VIBRATION PROOF

INTEL® CORE™ I7 HASWELL PROCESSOR,  
FANLESS RUGGED VIBRATION PROOF SYSTEM,  
MPCIIE EXPANSION, 9V TO 36V DC-IN,  
EXTENDED TEMP. -40~70°C



- MIL-STD-810G VIBRATION:10 GRMS, SHOCK: 75GRMS
- 4TH GENERATION INTEL® CORE™ I7 HASWELL PROCESSORS (BGA)
- DDR3 UP TO 8GB XR-DIMM
- MSATA UP TO 512GB
- MULTI-DISPLAYS BY 2 X DP, 1 X DVI-I
- 2X RJ45 INTEL® GIGABIT ETHERNET
- 1 X MPCIE EXPANSION
- 4 X USB 3.0, 1 X COM PORTS (1X RS232/422/485)
- 9V~36V DC-IN WITH POWER DELAY ON/OFF
- EXTENDED TEMPERATURE -40 TO 70 °C
- OPTIONAL FOR WIPE ROPE VIBRATION ISOLATOR

## SPECIFICATIONS

SPECIFICATIONS	
High Performance Processor	Intel® 4th Gen Core™ i7-4700EQ (Frequency 2.4GHz, Turbo Boost Frequency up to 3.4GHz), Quad-Core, 8 Thread Support, 6MB SmartCache. Build-in HD Graphics 4600 for excellent 3D , Turbo Boost Technology 2.0 , VPro and Hyper-Threading support.
Memory	1 x SAMTEC XR-DIMM™ Rugged Memory connector (BTH-120-01-L-D-A) with Swiss-bit® DDR3 1600MHz XR-DIMM up to 8GB ECC SDRAM
Chipset	Intel® QM87 Chipset providing integrated USB 3.0 and supporting 4th generation Intel® Core™ processor families
Expansion Slot	2 x Full-size miniPCIe (ACES 88911-5204M) ,one co-lay with mSATA for operating system, Rugged -40/+85C High Capacity Military-Grade mSATA up to 512GB. 1 x Onboard SIM Card slot (ASTRON 5190006-007-R) for 3.5G connectivity 1 x FPE connector (SAMTEC SEAF-20-06.0-L-10-2-A-K-TR) 1 x StackPC connector (SAMTEC ASP-129637-03)
DISPLAY	
Display Port	Resolution up to 3840 x 2160@60 Hz
DVI-I	Resolution up to 1920 x 1200@60 Hz
STORAGE	
mSATA	mSATA Solid State Disk (SSD) - up to 512GB Capacity Rugged Industrial NAND Flash mSATA Storage w/ Rugged -40/+85C High Capacity, optional Pre-loaded with Linux or Windows OS. 64 / 128 / 256 / 512GB Innodisk 3MG2-P Series MLC SATA III 6Gb/s Flash SSD, Rated for 520 MB/sec Sequential Read ; 350 MB/sec Write Max.
ETHERNET	
Ethernet	2 x Intel Gigabit Ethernet LAN Interfaces (10/100/1000Mbps)
REAR I/O	
DisplayPort	2 x 20Pin External connectors (Female)
DVI-I	1 x 29Pin DVI-I connector (Female)
Ethernet	2 x RJ45 Gigabit Ethernet LAN Interfaces
Audio	2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out)
Serial Port	1 x DB9 connector (RS-232/422/485)
USB Port	2 x USB3.0 standard-A connectors
FRONT I/O	
Button	Power Button
DC-IN	4P Rugged Terminal connector
Indicator LED	Power, HDD, LAN (Link/Active/Speed)
USB Port	2 x USB3.0 standard-A connectors

**APPLICATIONS, OPERATING SYSTEM**

Applications	Commercial and Military Platforms Requiring Compliance to MIL-STD-810G Embedded Computing, Process Control, Intelligent Automation and manufacturing applications where Harsh Temperature, Shock, Vibration, Altitude, Dust and EMI Conditions. Used in all aspects of the military
Operating System	Windows 7 x32/x64, Windows 8 x32/x64, Windows 10 x32/x64 Fedora 20 , Ubuntu ,13.04 , Ubuntu 13.10 , Ubuntu 14.04

**PHYSICAL**

Dimension (W x D x H)	250 x 149 x 69 mm
Weight	3.81 Kg (8.38 lbs)
Chassis	Aluminum Alloy, Corrosion Resistant.
Finish	Anodic aluminum oxide (Color Iron gray)
Cooling	Natural Passive Convection/Conduction. No Moving Parts.
Connectors	DC-IN : PHOENIX CONTACT 1776715 RJ45 Ethernet : RTB-19GB9J1A DVI-I : BANGSON DVI02-0123001-T DisplayPort : FOXCONN 3VD21203-H7U0-4 Audio : WTJ-035-67S1A01/ WTJ-035-67S1A02
Vibration Isolator	Wire Rope Isolator (Hongyuan GGT 2.1-23/GGT 2.7-25)
Ingress Protection	Dust Proof (Similar to IP50)

**ENVIRONMENTAL**

MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6 Shock-Procedure I Operating (Mechanical Shock) Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration) Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
Reliability	No Moving Parts; Passive Cooling. Designed & Manufactured using ISO 9001/2000 Certified Quality Program
EMC	CE and FCC certificated
Green Product	RoHS, WEEE compliance

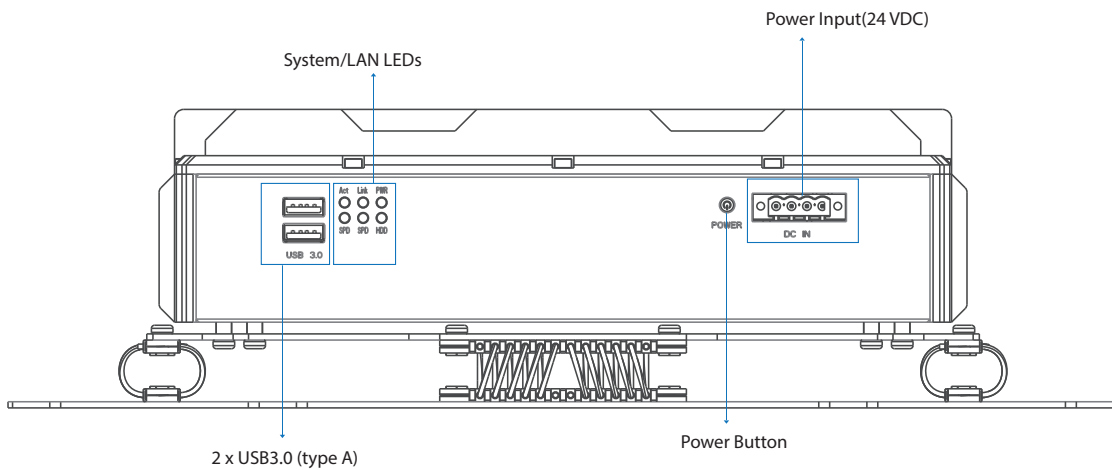
**ORDERING INFORMATION**
**SR10A**

**MIL-STD-810G RUGGED COMPUTER WITH INTEL® CORE™ I7-4700EQ, 9V TO 36V DC-IN, MINI PCIE, HIGH VIBRATION / SHOCK PROTECTION, EXTENDED TEMP. -40~70°C**

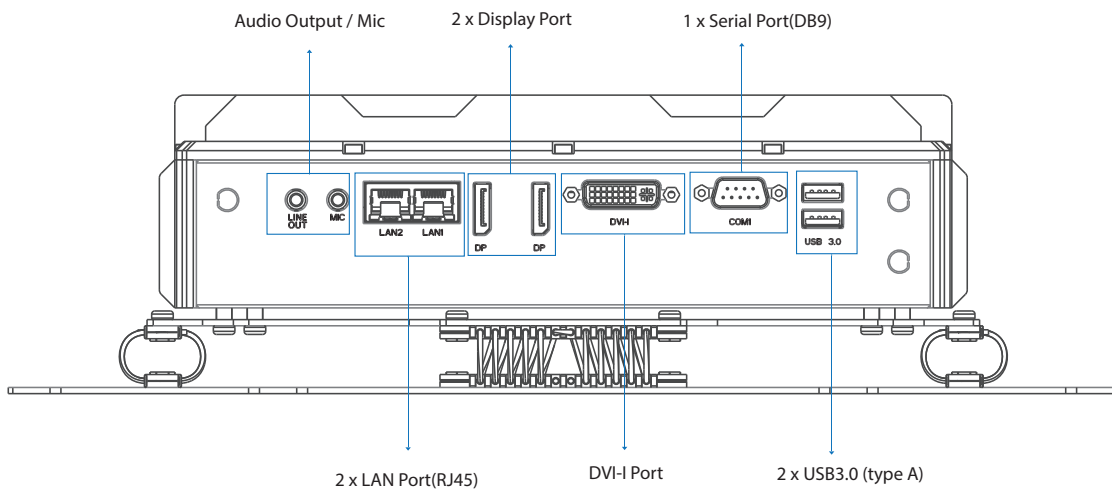
**SR10A** , A MIL-STD-810G STANDARD SYSTEM HIGHLIGHTS IN ITS 4TH GENERATION HASWELL CORE I7-4700QE FANLESS SYSTEM WITH RUGGED XR-DIMM RAM, RICH I/O WITH 4X USB 3.0, 1X COM PORT, 2X LAN, 3 VIDEO OUTPUTS AND MPCIe EXPANSION SLOT. BESIDES VARIETY OUTPUTS, PERFECTRON HAS DESIGN AN UNIQUE WIPE ROPE VIBRATION ISOLATOR FOR BETTER VIBRATION AND SHOCK RESISTANCE.

APPEARANCE

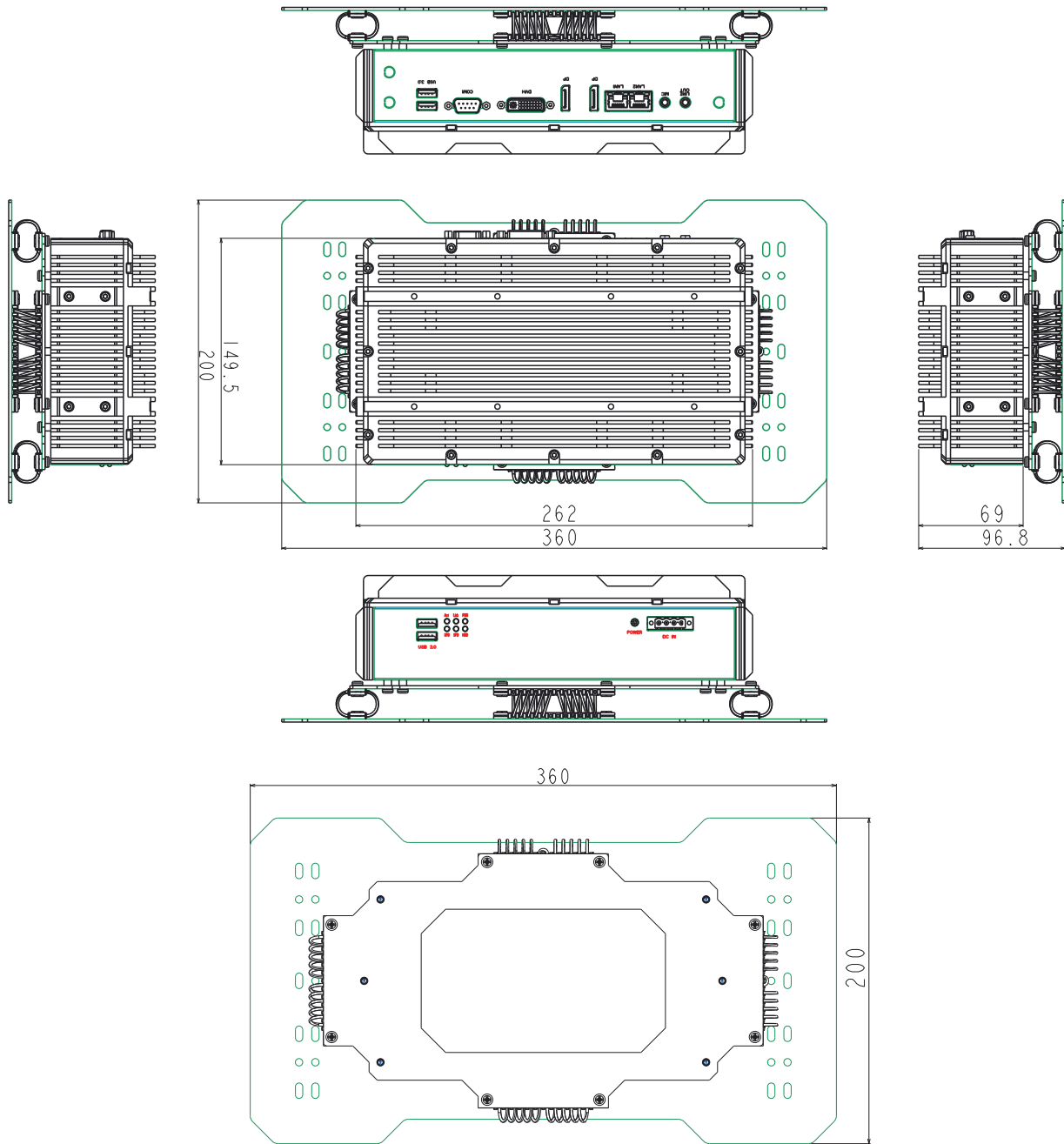
Front Side



Back Side



DIMENSIONS



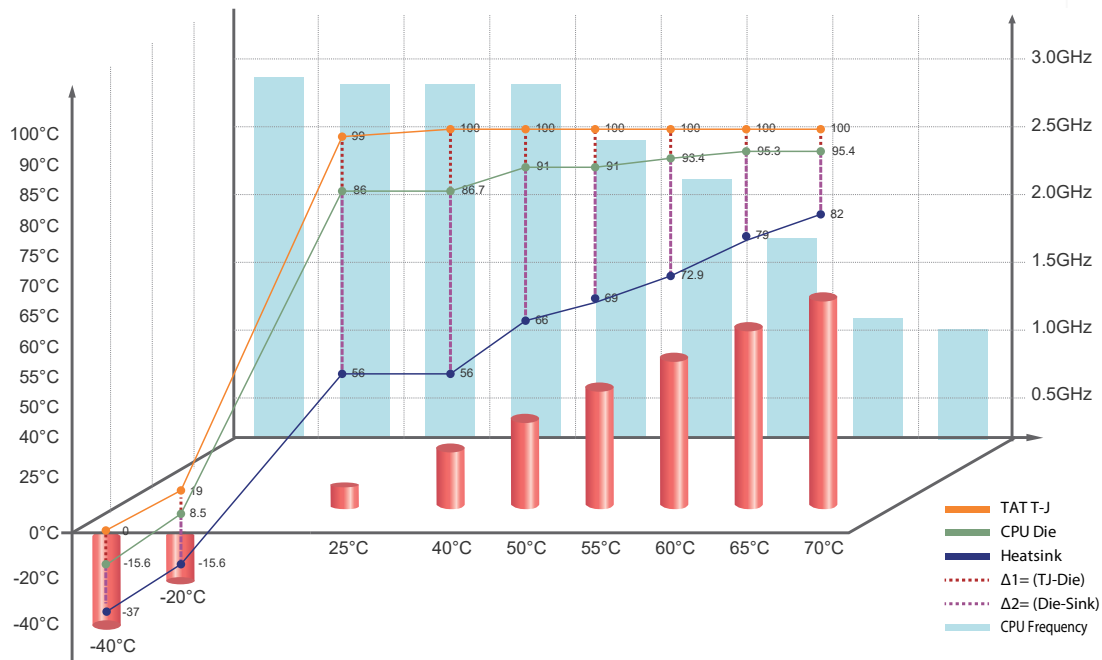
## TEST CONFIGURATION

ITEM	DEVICE INFORMATION
CPU Type	Intel® Core i7-4700EQ (4C x 2.4Ghz), 6M Cache (47W)
PCH	Intel® QM87
Memory	8GB DDR3 1600 MHz XR DIMM
mSATA PORT	innodisk 256GB MSATA
Test Software	Burnin test v7.1 Crystal DiskMARK3.03, Intel Extreme Tuning Utility 1

## TEST RESULT

Model	SR10A	Test Result	Pass
Tester	Ian Huang		

Diagram of curves	Test Temperature	Test Time
	High	0~70°C 3Hours
	Low	-40~0°C 2Hours
	Test Standard	Reference IEC60068-2
	Test Software	Burnin test v7.1
	Criteria	After testing, system can't halt.



SR10-1A MB HeatSink - IO Performance									
Point	-40°C	-20°C	25°C Room Temperature	40°C	50°C	55°C	60°C	65°C	70°C
CPU T-J	0	19	99	100	100	100	100	100	100
CPU Die	-15.6	8.5	86	86.7	91	91	93.4	95.3	95.4
Heat sink	-37	-15.6	56	56	66	69	72.9	79	82
Delta 1 = (TJ-Die)	15.6	10.5	13	13.3	9	9	6.6	4.7	4.6
Delta 2 = (Die-Heatsink)	21.4	24.1	30	30.7	25	22	20.5	16.3	13.4
CPU Frequency	2.82GHz	2.79GHz	2.79GHz	2.79GHz	2.39GHz	2.19GHz	1.7GHz	1.1GHz	1.0GHz